

ABSTRACT OF THE DISCLOSURE

Disclosed is a silver-plated copper alloy material for lead frames, which is excellent in solder-wettability. A silver-plated material for lead frames, wherein a silver-plating layer having an (a^* value + b^* value) of the $L^*a^*b^*$ colorimetric system within the range of 1.5 to 7 is made on a copper strip or a copper alloy strip. The thickness of the silver-plating layer is from 0.5 to 10 μm . Preferably, the copper strip or the copper alloy strip and the silver-plating layer have a nickel- or nickel alloy-plating layer therebetween.

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REPLACED